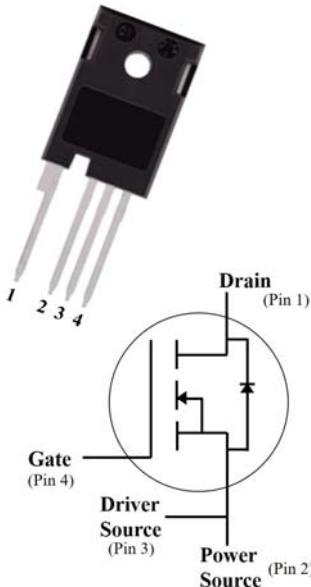


## Silicon Carbide Power MOSFET (N-Channel Enhancement)

$V_{DS}$	1200V
$I_D(25^\circ C)$	67A
$R_{DS(on)}$	34mΩ



### Features

- High speed switching
- Essentially no switching losses
- Reduction of heat sink requirements
- Maximum working temperature at 175 °C
- High blocking voltage
- Fast Intrinsic diode with low recovery current
- High-frequency operation
- Halogen free, RoHS compliant

### Typical Applications

Typical applications are in power factor correction(PFC), solar inverter, uninterruptible power supply, motor drives, photovoltaic inverter, electric car and charger.

### Mechanical Data

- **Package:** TO-247-4L
- **Terminals:** Tin plated leads
- **Polarity:** As marked

### ■Maximum Ratings ( $T_c=25^\circ C$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	VALUE	TEST CONDITIONS	NOTE
Device marking code				D212040NCFYG3	
Drain source voltage @ $T_j=25^\circ C$	$V_{DS,max}$	V	1200	$V_{GS}=0V, I_D=100\mu A$	
Gate source voltage @ $T_j=25^\circ C$	$V_{GS,max}$	V	-8/+22	Absolute maximum values	
Gate source voltage @ $T_j=25^\circ C$	$V_{GS,op}$	V	-4/+18	Recommended operational values	
Continuous drain current @ $T_c=25^\circ C$	$I_D$	A	67	$V_{GS}=18V, T_c=25^\circ C$	Fig.17
Continuous drain current @ $T_c=100^\circ C$			46	$V_{GS}=18V, T_c=100^\circ C$	
Pulsed drain current	$I_{D,pulsed}$	A	180	Pulse width $t_p$ limited by $T_{j,max}$	Fig.22
Avalanche energy,Single Pulse	$E_{AS}$	mJ	785	$V_{DD}=75V, L=30mH$	
Power Dissipation	$P_{TOT}$	W	333	$T_c=25^\circ C, T_j = 175^\circ C$	Fig.16
Power Dissipation			165	$T_c=100^\circ C, T_j = 175^\circ C$	
Operating junction and Storage temperature range	$T_j, T_{stg}$	°C	-55 to +175		
Soldering temperature	$T_L$	°C	260	1.6mm (0.063") from case for 10s	
Mounting torque	$T_M$	Nm	0.6	M3 screw Maximum of mounting process: 3	



# YJD212040NCFYG3

## ■ Static Electrical Characteristics (Tc=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Gate threshold voltage	V <sub>GS(th)</sub>	V	2.0	3.0	4.0	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = 12mA	Fig.4, 11
				2.2		V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = 12mA, Tj=175°C	
Drain source breakdown voltage	V <sub>(BR)DSS</sub>	V	1200			V <sub>GS</sub> =0V, I <sub>D</sub> =100uA	
Gate source leakage current	I <sub>GSS</sub>	nA		10	100	V <sub>GS</sub> = 18V, V <sub>DS</sub> =0V	
Current drain source on-state resistance	R <sub>DS ON</sub>	mΩ		34	42	V <sub>GS</sub> =18V, I <sub>D</sub> =30A	Fig.5, 6, 7
				56		V <sub>GS</sub> =18V, I <sub>D</sub> =30A, Tj=175°C	
Transconductance	g <sub>f</sub>	S		19		V <sub>DS</sub> =20V, I <sub>D</sub> =30A	Fig.4
				18		V <sub>DS</sub> =20V, I <sub>D</sub> =30A, Tj=175°C	

## ■ Dynamic Electrical Characteristics (Tc=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Input capacitance	C <sub>iss</sub>	pF		3362		V <sub>DS</sub> =1000V, V <sub>GS</sub> =0V, Tj=25°C, f=1MHz, V <sub>AC</sub> = 25mV	Fig.13, 14
Output capacitance	C <sub>oss</sub>			119			
Reverse capacitance	C <sub>rss</sub>			5.4			
C <sub>oss</sub> stored energy	E <sub>oss</sub>	uJ		85			Fig.15
Gate source charge	Q <sub>gs</sub>	nC		31		V <sub>DS</sub> =1000V, V <sub>GS</sub> =-4/+18V, I <sub>D</sub> =30A	Fig.12
Gate drain charge	Q <sub>gd</sub>			58			
Gate charge	Q <sub>g</sub>			117			
Internal gate resistance	R <sub>g</sub>	Ω		1.6		f=1MHz	

## ■ Switching Characteristics (Tc=25°C unless otherwise specified)

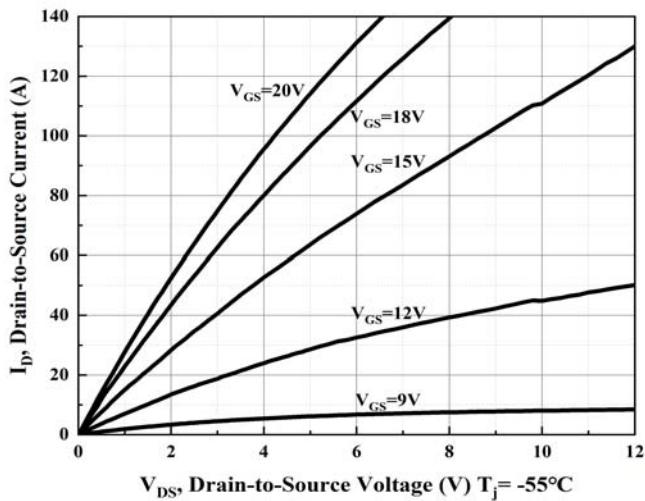
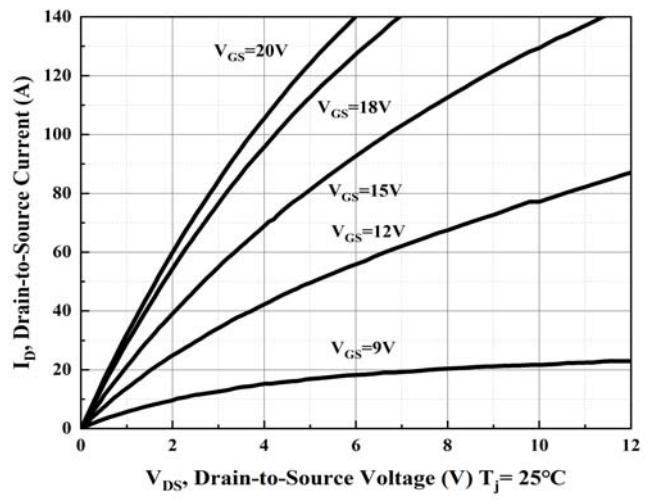
PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Turn on switching energy	E <sub>on</sub>	uJ		363		V <sub>DD</sub> =1000V, V <sub>GS</sub> =-4/+18V, I <sub>D</sub> =30A, R <sub>g</sub> =2.4Ω, L=100uH	Fig.19, 20
Turn off switching energy	E <sub>off</sub>			95			
Turn on delay time	t <sub>d(on)</sub>	ns		11		V <sub>DD</sub> =1000V, V <sub>GS</sub> =-4/+18V, I <sub>D</sub> =30A, R <sub>g</sub> =2.4Ω, L=100uH	Fig.21
Rise time	t <sub>r</sub>			17			
Turn off delay time	t <sub>d(off)</sub>	ns		28			
Fall time	t <sub>f</sub>			11			

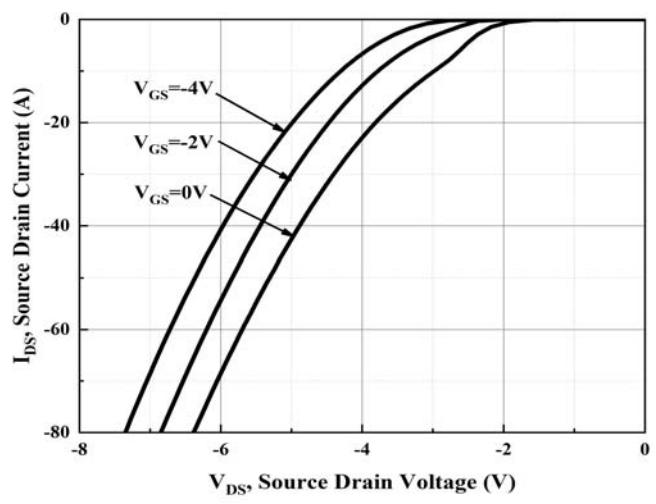
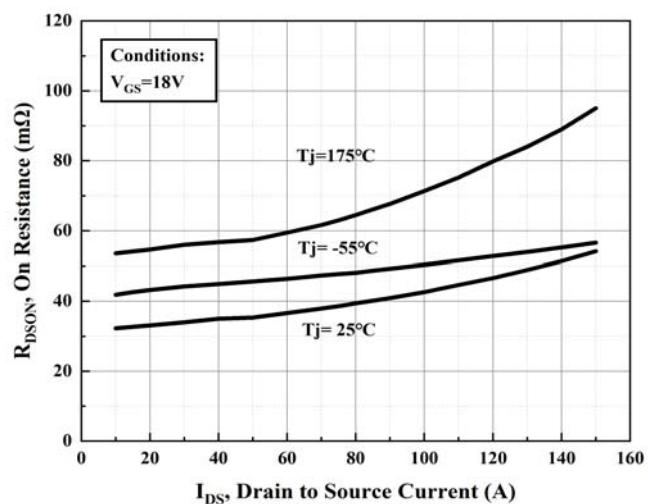
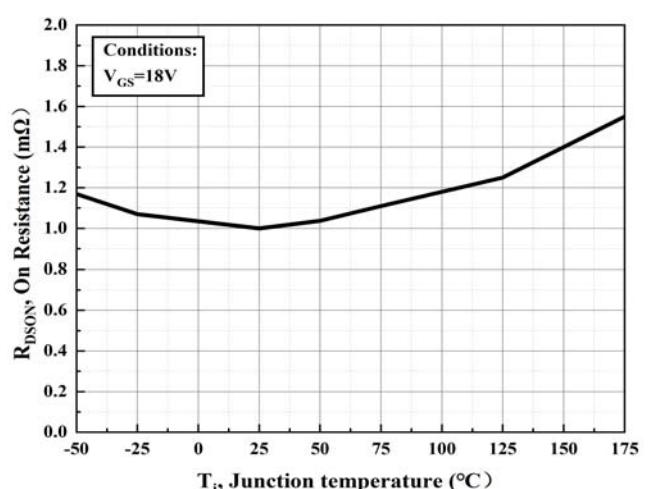
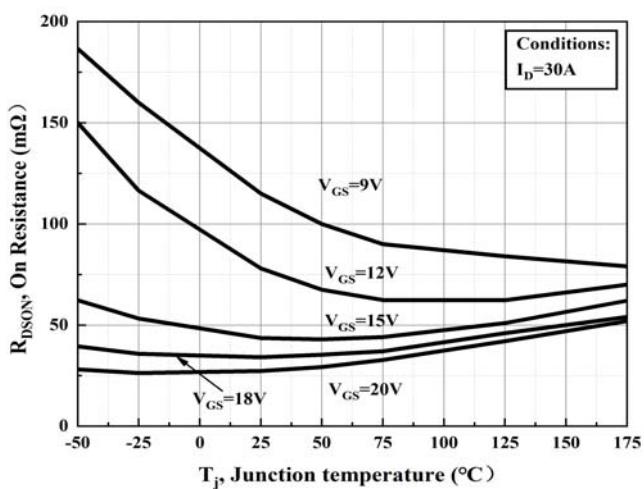
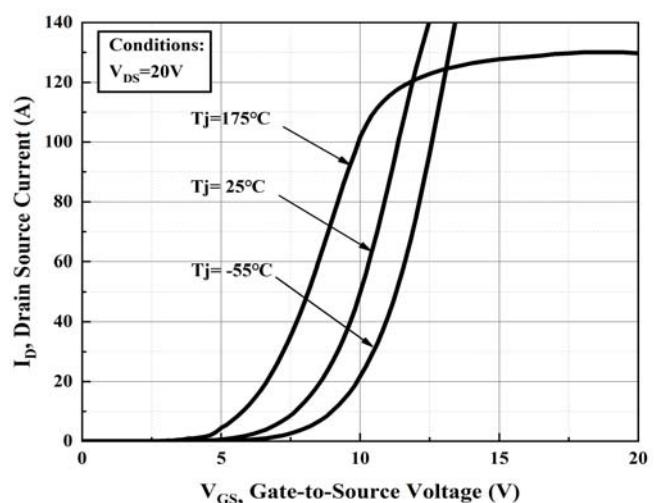
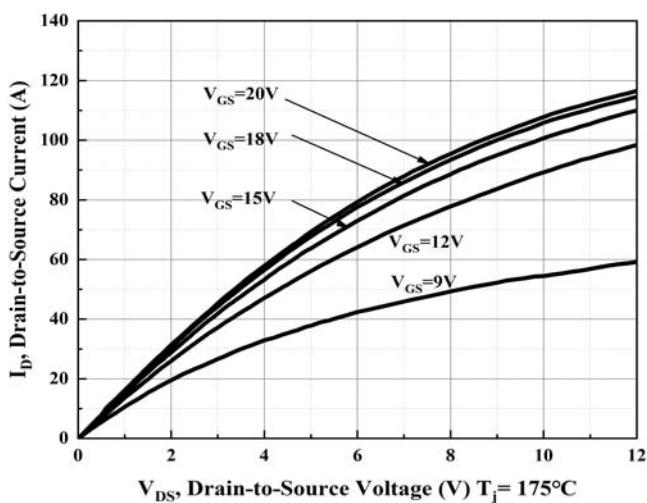
**■Body diode characteristics (T<sub>c</sub>=25°C unless otherwise specified)**

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Diode forward voltage	V <sub>SD</sub>	V		4.7		V <sub>GS</sub> =-4V, I <sub>SD</sub> =15A	Fig.8
				3		V <sub>GS</sub> =0V, I <sub>SD</sub> =15A, T <sub>j</sub> =175°C	Fig.9
Continuous diode forward current	I <sub>S</sub>	A		65		T <sub>c</sub> =25°C	
Reverse recovery time	trr	nS		17		V <sub>R</sub> =800V, V <sub>GS</sub> =-4V, I <sub>D</sub> =30A, di/dt=2000A/uS	
Reverse recovery charge	Qrr	nC		178			
Peak reverse recovery current	Irrm	A		16			

**■Thermal Characteristics (T<sub>a</sub>=25°C Unless otherwise specified)**

PARAMETER	SYMBOL	UNIT	Typ.
Thermal resistance	R <sub>θJ-C</sub>	°C /W	0.45

**■Typical Characteristics**

 Figure 1. Output Characteristics T<sub>j</sub> = -55°C

 Figure 2. Output Characteristics T<sub>j</sub> = 25°C



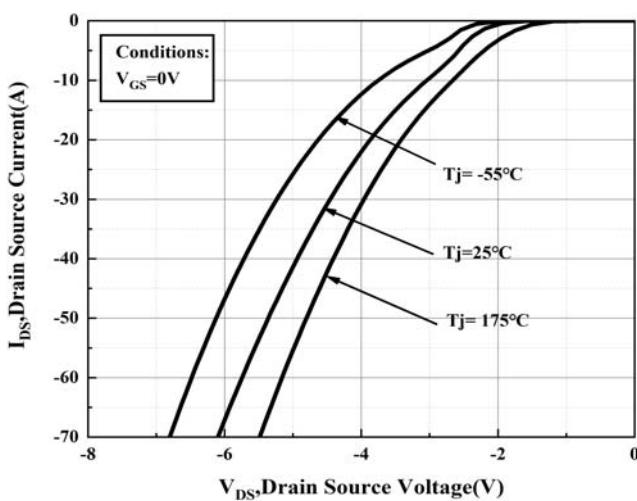


Figure 9. Body Diode Characteristic

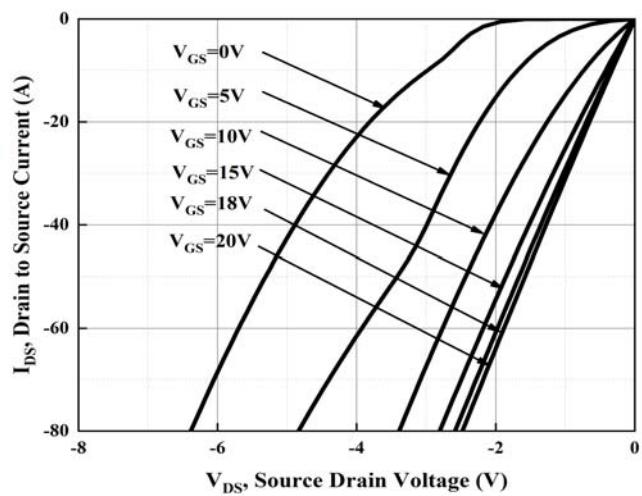


Figure 10. 3<sup>rd</sup> quadrant Characteristic at  $T_j = 25^\circ C$

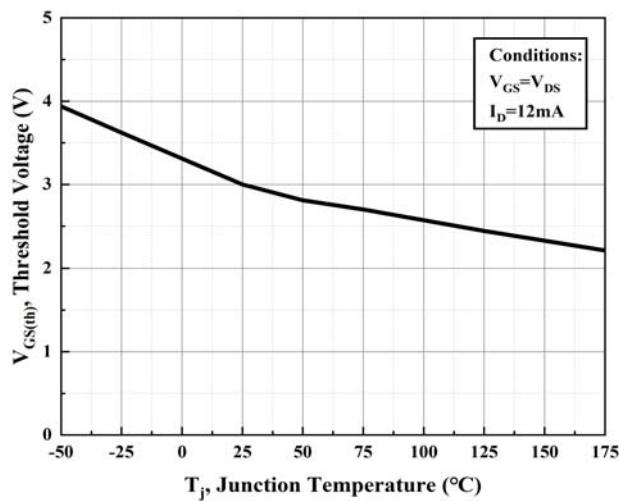


Figure 11. Threshold Voltage vs. Temperature

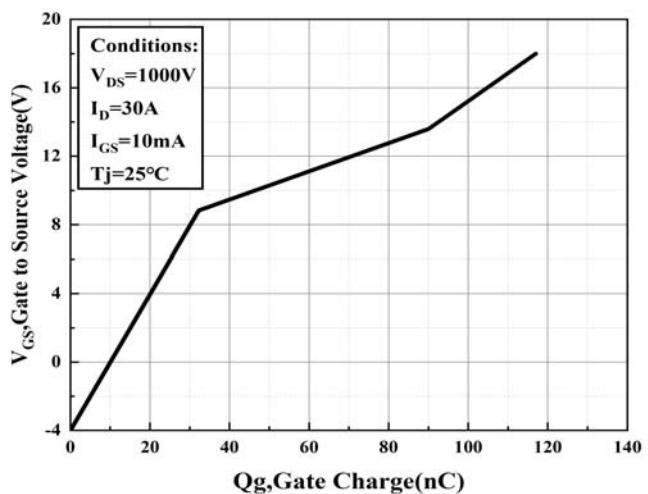


Figure 12. Gate Charge Characteristic

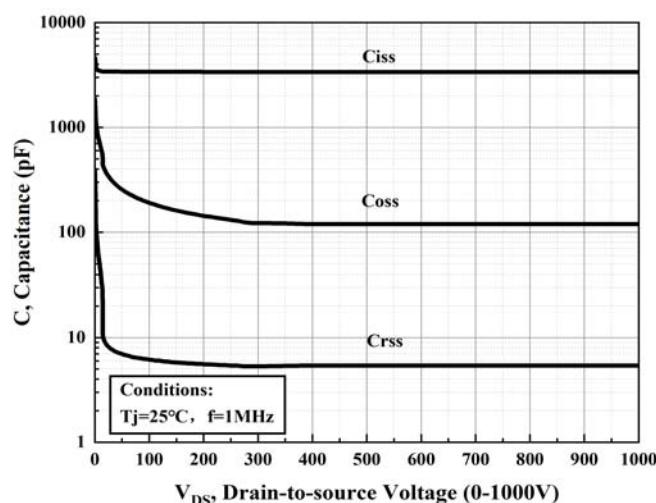


Figure 13. Capacitances vs. Drain Source Voltage (0-1000V)

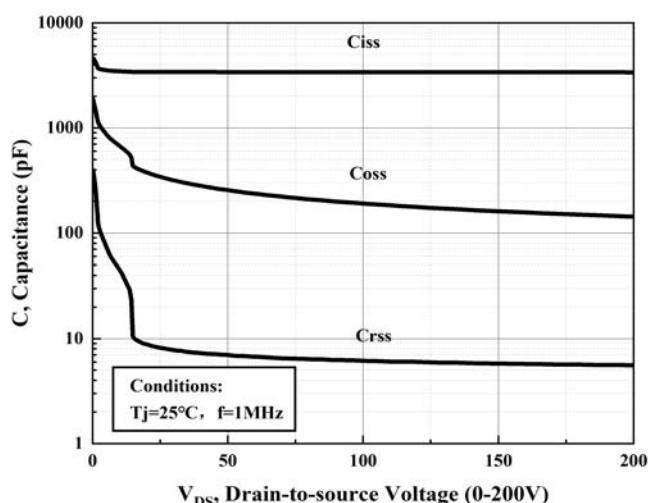


Figure 14. Capacitances vs. Drain Source Voltage (0-200V)

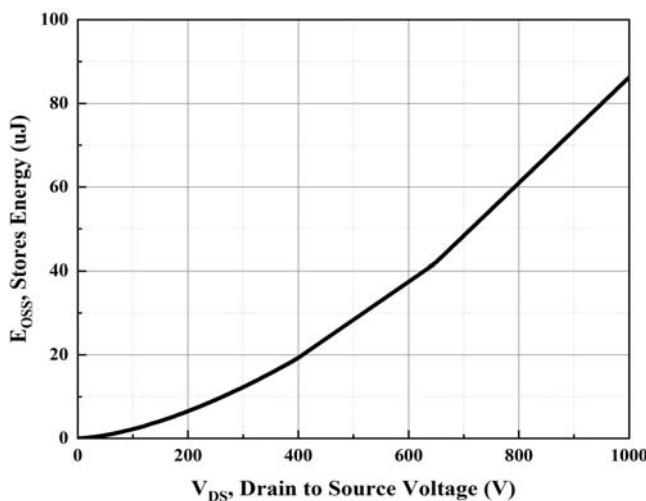


Figure 15. Output Capacitor Stored Energy

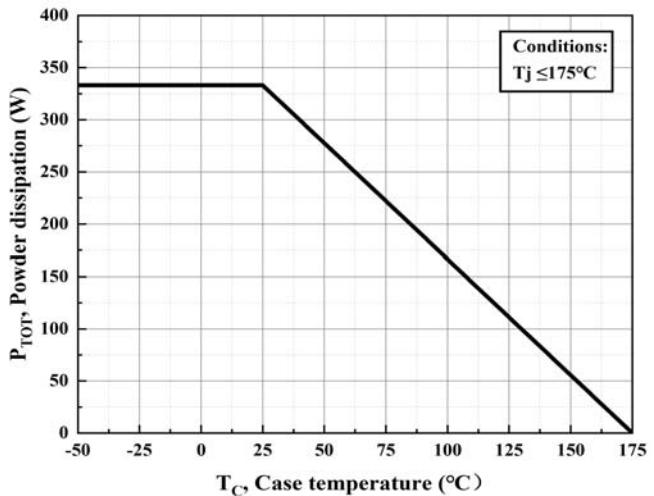


Figure 16. Maximum Power Dissipation Derating vs. Case Temperature

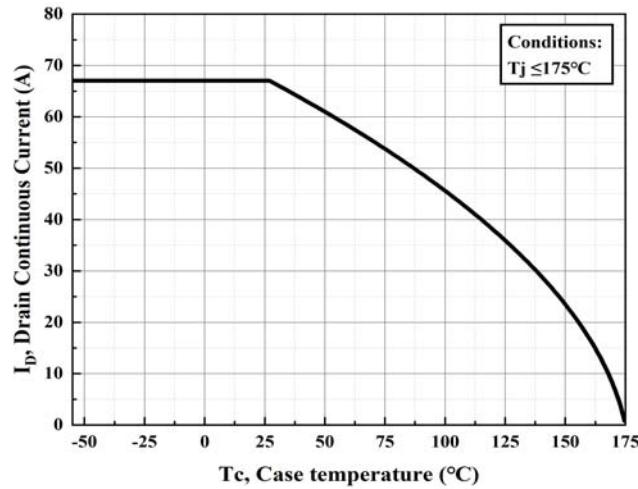


Figure 17. Continuous Drain Current Derating vs. Case Temperature

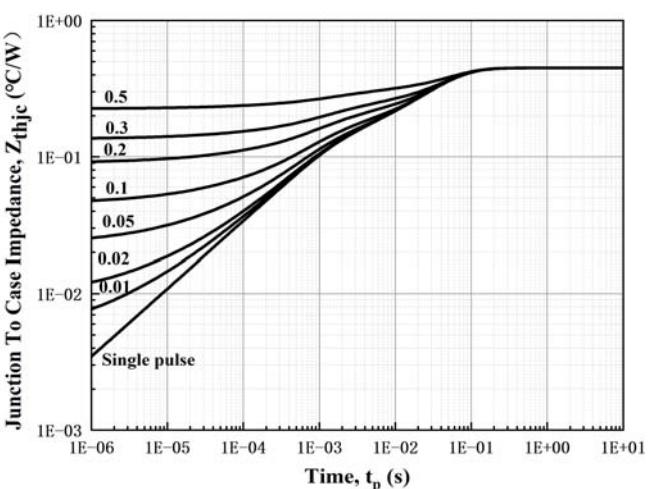


Figure 18 Transient Thermal Impedance (Junction - Case)

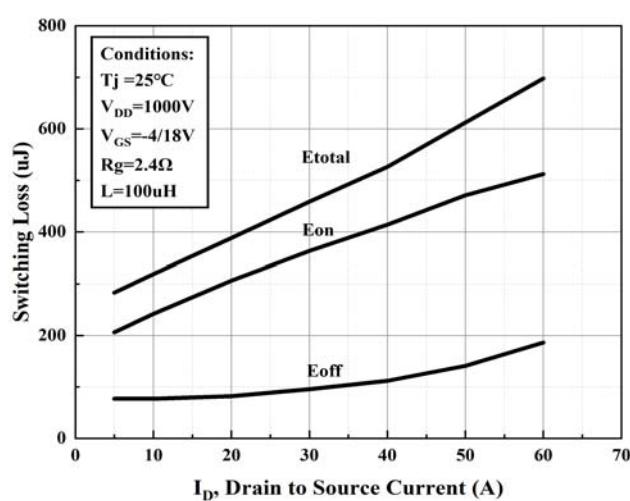


Figure 19. Clamped Inductive Switching Energy vs. Drain Current

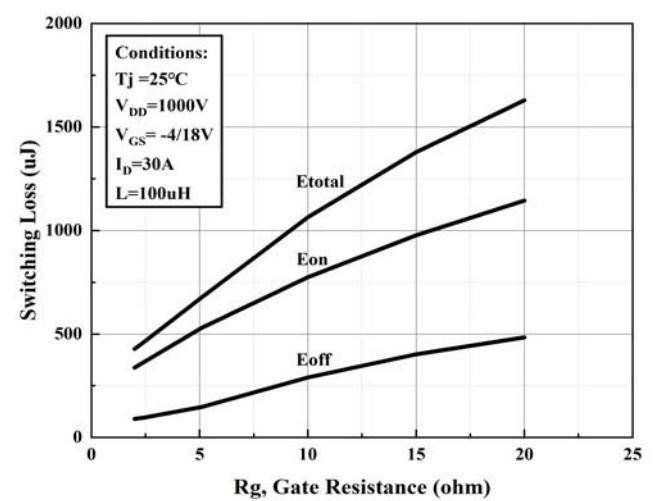


Figure 20. Clamped Inductive Switching Energy vs.  $R_g$

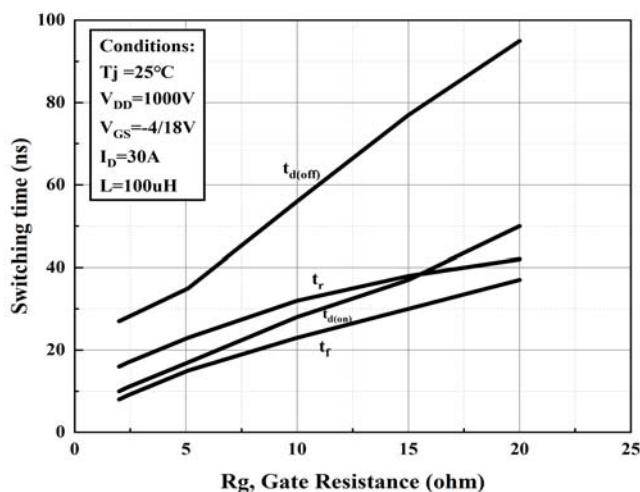


Figure 21. Switching Times vs.  $R_g$

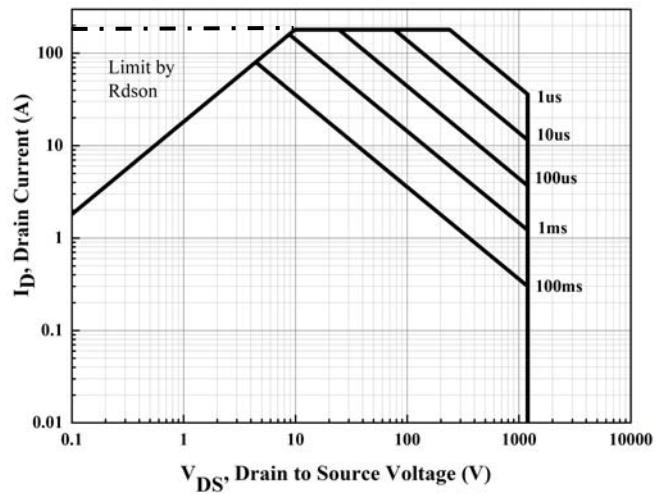


Figure 22. Safe Operating Area

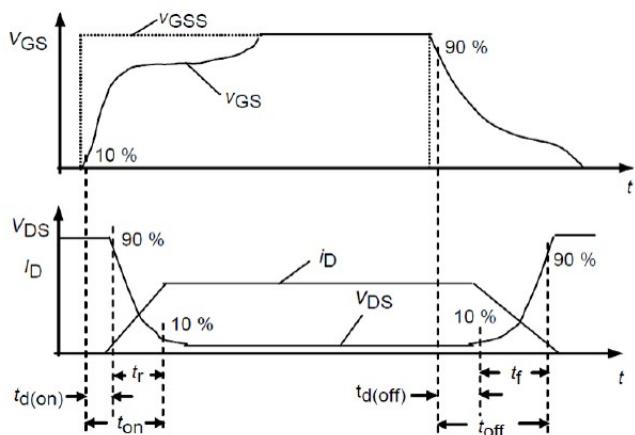


Figure 23. Switching Times Definition

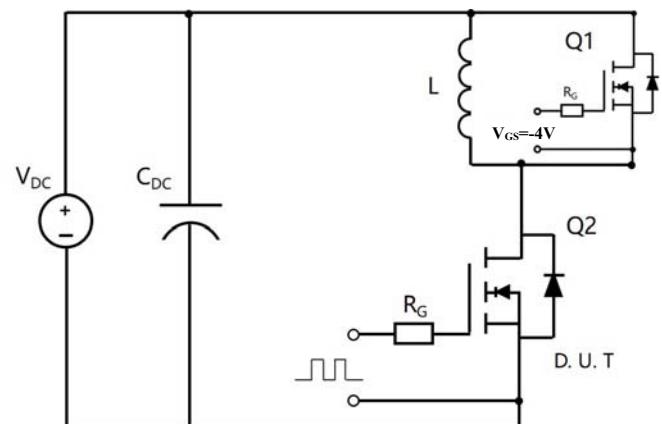
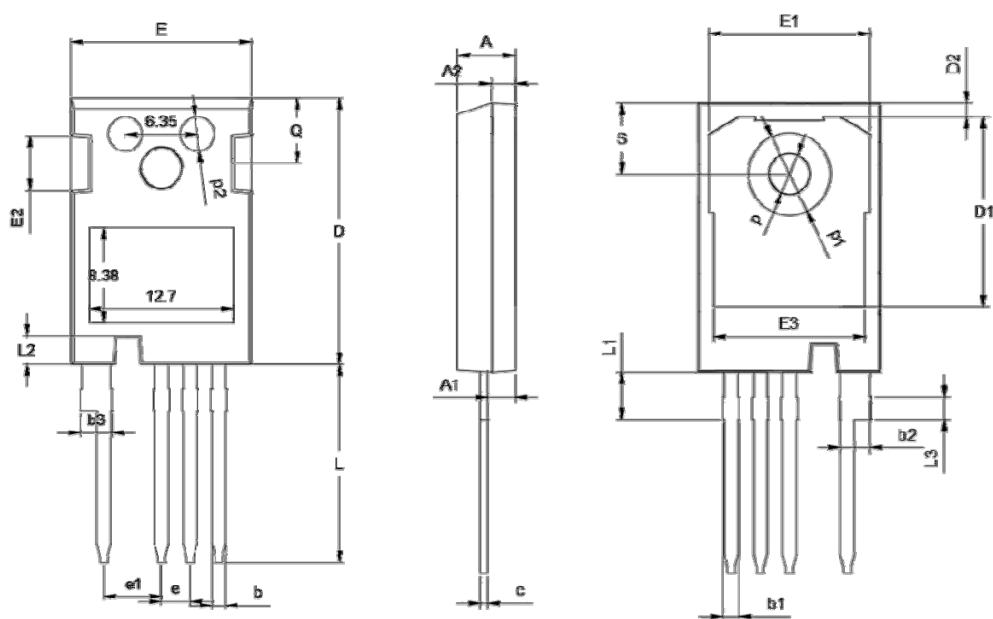


Figure 24. Clamped Inductive Switching Waveform Test Circuit



## ■Outline Dimensions



TO247-4L			
Dim	Min	Norm	Max
A	4.80	5.00	5.20
A1	2.30	2.40	2.50
A2	1.88	1.98	2.08
b	1.10	1.20	1.30
b1	1.20	/	1.50
b2	2.35	2.55	2.75
b3	2.45	/	2.85
c	0.55	0.60	0.65
D	23.3	23.45	23.6
D1	16.25	16.55	16.85
D2	1.00	/	1.30
e	TYP2.54		
e1	TYP5.06		
E	15.75	15.90	16.05
E1	13.80	/	14.20
E2	4.40	4.75	5.10
E3	13.00	/	13.45
L	17.34	17.49	17.64
L1	4.00	/	4.30
L2	2.35	/	2.65
L3	TYP1.98		
Q	5.60	5.80	6.00
S	6.05	/	6.30
p	TYP3.58		
p1	TYP7.18		
p2	TYP3.00		



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